

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ065N03LS	**Issued**	08. February 2022
MA#	MA005420965		
Package	PG-TSDSON-8-25	**Weight***	35.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.194	0.55	0.55	5498	5498
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70	
	non noble metal	zinc	7440-66-6	0.010	0.03		279	
	non noble metal	iron	7439-89-6	0.197	0.56		5573	
	non noble metal	copper	7440-50-8	7.988	22.63	23.23	226298	232220
wire	noble metal	gold	7440-57-5	0.031	0.09	0.09	865	865
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1087	
	plastics	epoxy resin	-	1.975	5.60		55958	
	inorganic material	silicondioxide	60676-86-0	17.164	48.61	54.32	486240	543285
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11197	11197
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	576	576
solder	non noble metal	tin	7440-31-5	0.007	0.02		188	
	noble metal	silver	7440-22-4	0.008	0.02		235	
	non noble metal	lead	7439-92-1	0.317	0.90	0.94	8987	9410
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2065	
	non noble metal	copper	7440-50-8	2.959	8.38	8.60	83828	86022
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2662	
	non noble metal	copper	7440-50-8	3.816	10.81	11.09	108099	110927
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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